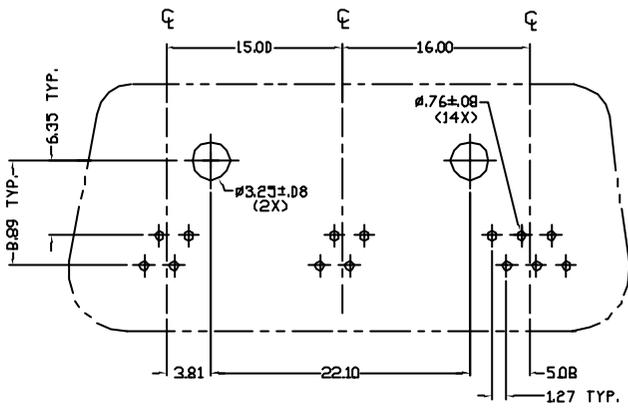


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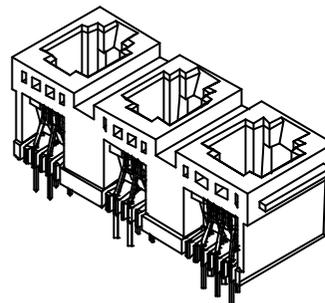
PCB FOOTPRINT LAYOUT

CPC	DIMENSION						
	'A'	'B'	'C'	'D'	'E'	'F'	'G'
FT600541	2.41	3.82	11.18	3.81	3.05	5.59	7.87
FT600541LF	2.41	3.82	11.18	3.81	3.05	5.59	7.87
FT658160	2.41	3.82	11.18	3.81	3.05	5.59	7.87
FT658160LF	2.41	3.82	11.18	3.81	3.05	5.59	7.87
FT684947	2.41	2.81	13.21	2.79	4.06	6.69	9.88
FT684947LF	2.41	2.81	13.21	2.79	4.06	6.69	9.88

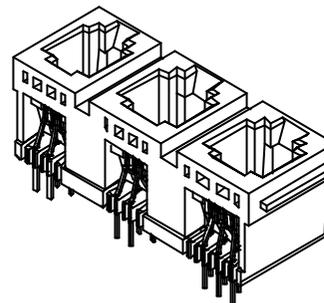
CPC	POSITIONS LOADED			PACKAGING
	JACK A	JACK B	JACK C	
FT600541	ALL	ALL	C2,C3,C4,C5	TUBE
FT600541LF	ALL	ALL	C2,C3,C4,C5	TUBE
FT658160	ALL	ALL	ALL	TUBE
FT658160LF	ALL	ALL	ALL	TUBE
FT684947	ALL	B1,B2,B3,B4	C2,C3,C4,C5	TUBE
FT684947LF	ALL	B1,B2,B3,B4	C2,C3,C4,C5	TUBE

NOTES:

- REGULATORY APPROVALS:
 - * RECOGNIZED TO U.S. AND CANADIAN REQUIREMENTS UNDER THE COMPONENT RECOGNITION PROGRAM OF Underwriters Laboratories Inc.
 - * CERTIFIED BY THE Canadian Standard Association.
- INSIDE CAVITIES ARE CONFORMED WITH FCC RULES PART 68, SUBPART "F".
- THESE DIMENSIONS APPLY OVER ENTIRE PROTRUDING HEIGHT OF THE TERMINAL.
- HOUSING MATERIAL: HIGH TEMP. THERMOPLASTIC, COLOR - BLACK, UL94V-0.
- CONTACT MATERIAL: PHOSPHOR BRONZE
MATING AREA PLATING: Au OVER Ni
SOLDER AREA PLATING: Sn/Pb OVER Ni,
EXCEPT FOR PART NUMBER WITH LF ON END.



600541 & 658160 SERIES ONLY



684947 SERIE

LEAD FREE SOLDER TAIL PLATING 2um(80uin)
MIN MATTE TIN OVER 1.27um(50uin) MIN NICKEL UNDERPLATE.

- THE JACKS WERE REPLACED BY "FG" OR "FT" DEPENDING OF PACKAGING METHOD (TUBE/GPAX).
- THIS PRODUCT COVERED BY PRODUCT SPEC. GS-12-083.
- MATES WITH FCC PART 68 PLUGS
4/4,4/4,6/6 FULLY LOADED - TOP ENTRY
4/4,4/4,4/6 SELECT LOADED - TOP ENTRY
4/4,4/6,4/6 SELECT LOADED - TOP ENTRY
PRESS-FIT (STANDARD) RETENTION PEGS
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MIN THICK CIRCUIT BOARD. SLIGHT DEFORMATION MAY OCCUR FOR THE DIAMOND PEGS AT 260-265° C WHICH WILL NOT AFFECT THE FUNCTION OF THE PRODUCT.
- PACKAGING OF LEAD FREE PRODUCTS MEETS LABELING AND PACKAGING SPECIFICATION GS-14-920.
- LEAD FREE PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

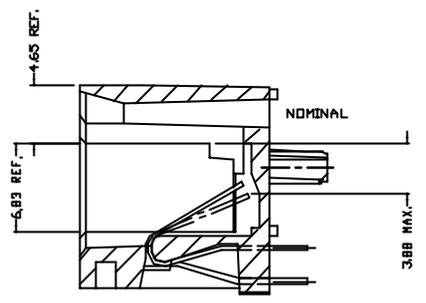
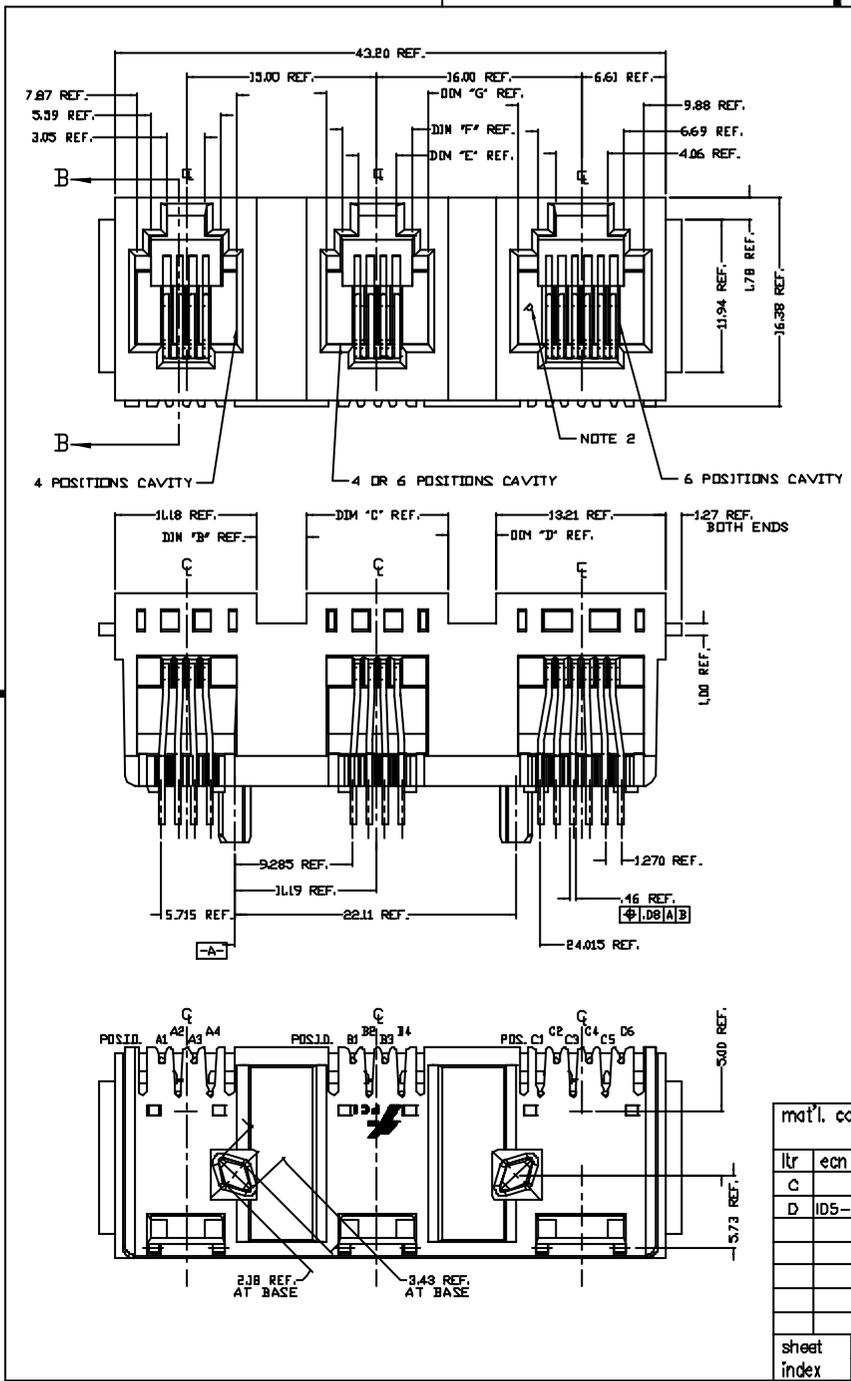
mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com
ltr	ecn no	dr	date	linear	X.X ±0.3		
A	V20906	JRV	5/10/02	linear	X.XX ±0.10		
B	V04-0323	DAI	5/17/04	angles	X.XXX ±0.050		product family MOD JACK
C	V05-0420	VS	10/5/05	angles	0° ±2°	size	code 213
D	ID5-0255	HVN	28/11/05	dr	J.R.VOLSTORF 4/30/02	MM	sheet 1 of 2
				engr	J.R.VOLSTORF 4/30/02	scale 1:1	A 58111
				chr	Hiran V N 11/28/05		
				appr	K.Somasundaram 1/28/05		
sheet index	revision sheet	D D	D D				
		1	2				

code code 22526

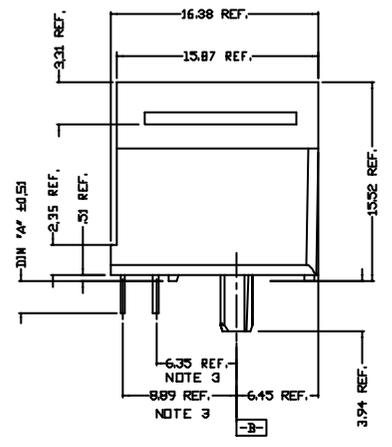
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SECTION B-B



ALL VIEWS ONLY DEPICT JACK (4/4/6) FULLY LOADED

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com	
ltr	ecn no	dr	date	linear	X.X ±0.3	projection	title
C				linear	X.XX ±0.10		4/4/6 & 4/6/6 POS. VERTICAL JACK ASSEM.
D	105-0255	HVN	28/11/05	angles	X.XXX ±0.050		product family
					0° ±2°	size	dwg no
				dr	J.R.VOLSTORF 4/30/02	scale	213
				enfr	J.R.VOLSTORF 4/30/02	A	58111
				chr	Hiran V N 28/11/05		
				appd	K.Somasundaram 28/11/05		
sheet index	revision sheet	D	2				

code code
22526

ACAD

PDM: Rev:D

STATUS:Released

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